

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	993	(chip adj packag\$3) and chip and substrate and (lead adj frame) and wir\$3	USPAT; EPO; JPO; DERWENT	OR	OFF	2005/04/27 10:51
L2	0	1 and bobding adj pad\$1	USPAT; EPO; JPO; DERWENT	OR	OFF	2005/04/27 10:51
L3	382	1 and bonding adj pad\$1	USPAT; EPO; JPO; DERWENT	OR	OFF	2005/04/27 10:52
L4	341	3 and @pd<="20040505"	USPAT; EPO; JPO; DERWENT	OR	OFF	2005/04/27 10:53